

ABSTRACT OF THE DISCLOSURE
INTEGRATED CIRCUIT TEST SOCKET

Disclosed is an improved integrated circuit socket having electrically
5 conductive pads formed on a resilient circuitry component for contacting the terminals of an
integrated circuit (IC) package which is positioned on the resilient circuitry. The
electrically conductive pads are arranged around the center area of the resilient circuitry to
be in one-to-one correspondence with the terminals of the IC package. The electrically
conductive pads have individual circuit paths of substantially the same length and which are
10 extending outwardly from the center area of the flexible circuitry, and additional electrically
conductive pads are formed on the back side of the flexible circuitry in order to effect the
required electrical connections to exterior circuits. These electrically conductive pads on
the back side are connected to the conductor pattern on the front side by conductive through
holes or vias. With this arrangement all conductors have the same, reduced inductance. An
15 insulative apertured film is preferably positioned intermediate the IC package and the
flexible circuitry having the electrically conductive pads in order to perform certain
alignment and pressure application functions.